Product End-of-Life Disassembly Instructions

Product Category: Data Storage Devices
Marketing Name / Model [List multiple models if applicable.]
AF728A & AG167A - HP 61xx Virtual Library Systems
AF729A & AG168A - HP 65xx Virtual Library Systems
AG051A & AG169A - HP 68xx Virtual Library Systems
AF730A, AG170A, AH813A - HP 6000 Virtual Lib Capacity Bundles

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	21 to 48 depending on config
Batteries	All types including standard alkaline and lithium coin or button style batteries	4 to 8 depending on config
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring		15 to 49

greater than 2.5 cm in diameter or height		depending on config
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Philips Philips Screw Driver	#1
Philips Screw Driver	#2
Flat Head Screw Driver Medium	Medium
Torx Drive	T-15

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. First disassembe the Storage Enclosure (MSA20) by performng the disassemble the batteries as shown below.
2. Disassemble the power supply using No. 1 philips screw driver. Remove 4 electrolytic capacitors from each power supply.
3. Next dissasemble the DL360G4p Serveras shown below.
4. System Board Battery – Remove the top cover and locate the battery on the system board. With a medium flat head screw driver remove the battery and dispose of properly.
5. SAS Controller Battery – Remove the riser board assembly from the system with a T-15 torx driver. Remove the SAS controller from the riser assembly then with a medium flat head screw driver remove the battery and dispose of properly.
6. Capacitors > 2.5CM – Remove the power supply(s) from the system. With #2 Philips screw driver remove the screws securing the top cover and the heatsinks in the P/S then locate the capacitors and pry from the PCB with a medium flat head screw driver and dispose of properly.
7.
8.
9.
10.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Controller Module

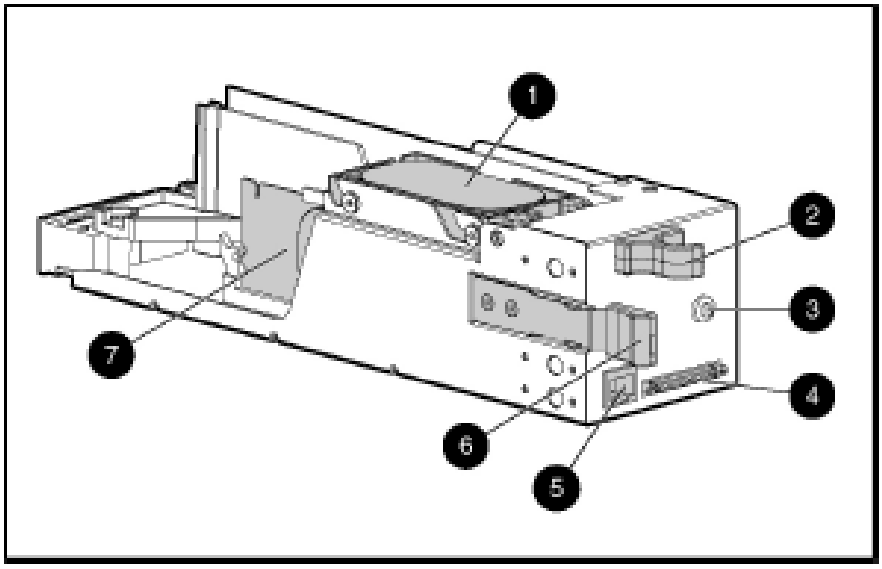
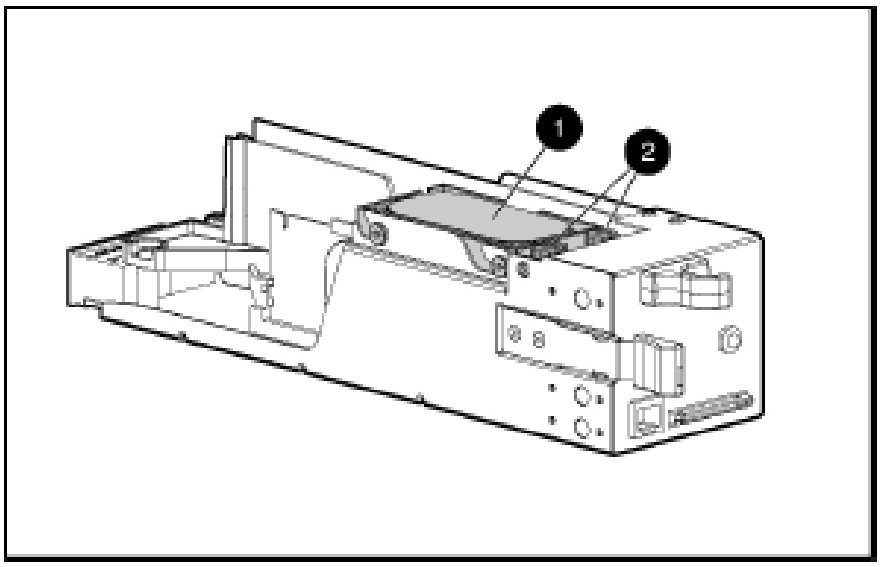


Figure 2-4: Controller module

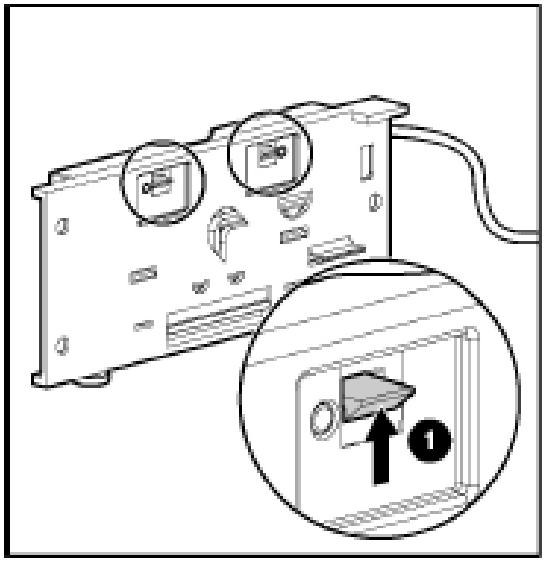
Item	Description
1	Upper cache battery
2	Finger hook
3	Bicolor status LED (green or amber)
4	VHDCI connector (for connecting to a sixth-generation Smart Array controller or an MSA1500 cs enclosure)
5	Service port (for HP service technicians only)
6	Release lever
7	Controller cache (lower cache battery just visible)

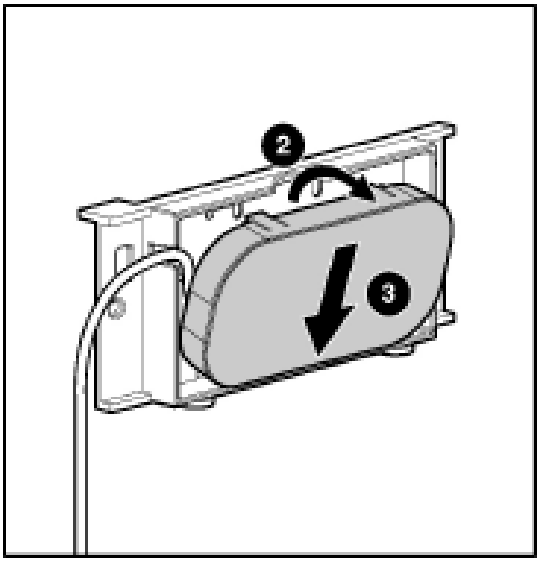
To replace the upper battery pack (1):

1. Remove the controller module from the enclosure (for detailed instructions, refer to the Controller Module section).
2. Loosen the thumbscrews (2).



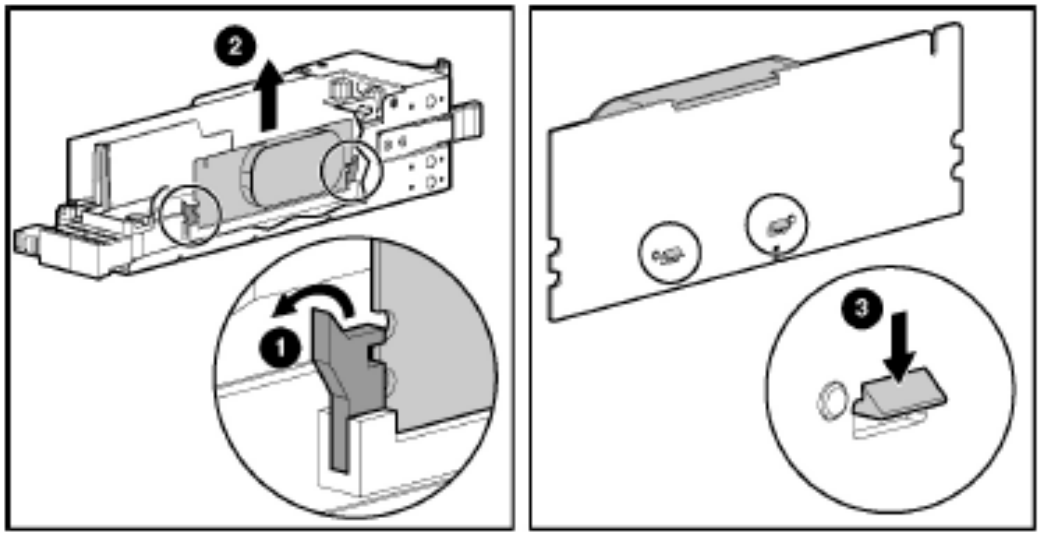
3. Slide the battery unit toward the rear of the controller module and lift it out.
4. On the back of the battery unit, push the two plastic retainer tabs upward through the slots in the battery case (1).
5. Tilt the battery pack slightly away from the battery case (2).
6. Press down on the battery pack to expel it from the battery case (3).





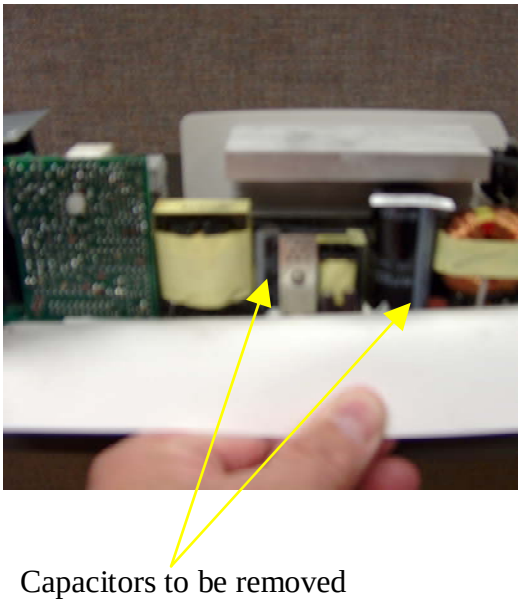
To replace the lower battery pack:

1. Remove the upper battery unit. (You do not need to dismantle the upper unit unless you must also replace the upper battery pack.)
2. Remove the cache board.
   a. Open the ejector levers on each side of the memory module socket (1).
   b. Pull the cache board out of the socket (2).
3. Push the plastic retainer tabs through to the other side of the cache board (3).



4. Lift the battery pack off the cache board.

Locate four capacitors for each power supply.
Two caps shown are for reference.



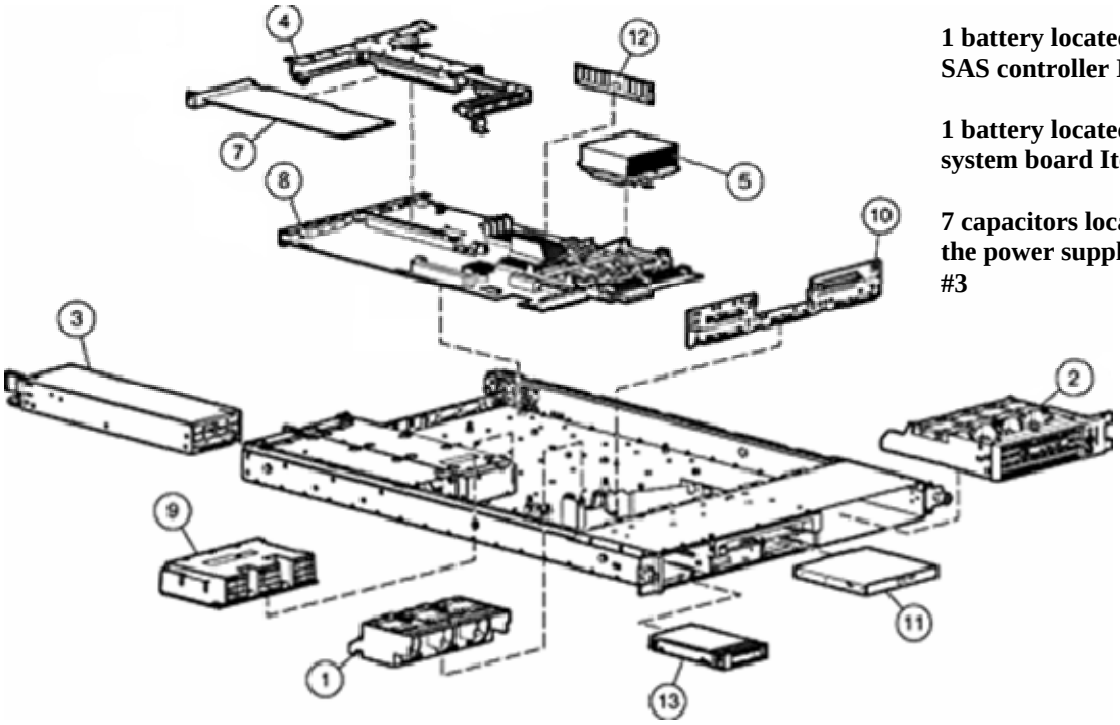
Capacitors to be removed

End of the MSA20 disassembly procedures.

Proliant DL360 G4p Instructions

Begin DL360G4p disassembly details. The following attachments depict the appropriate locations for action::

- Attachment 1 – Disassembly Diagram,
- Attachment 2 – System Battery Location
- Attachment 3 & 4 – SAS Battery Location
- Attachment 5 & 6 – Capacitors Location

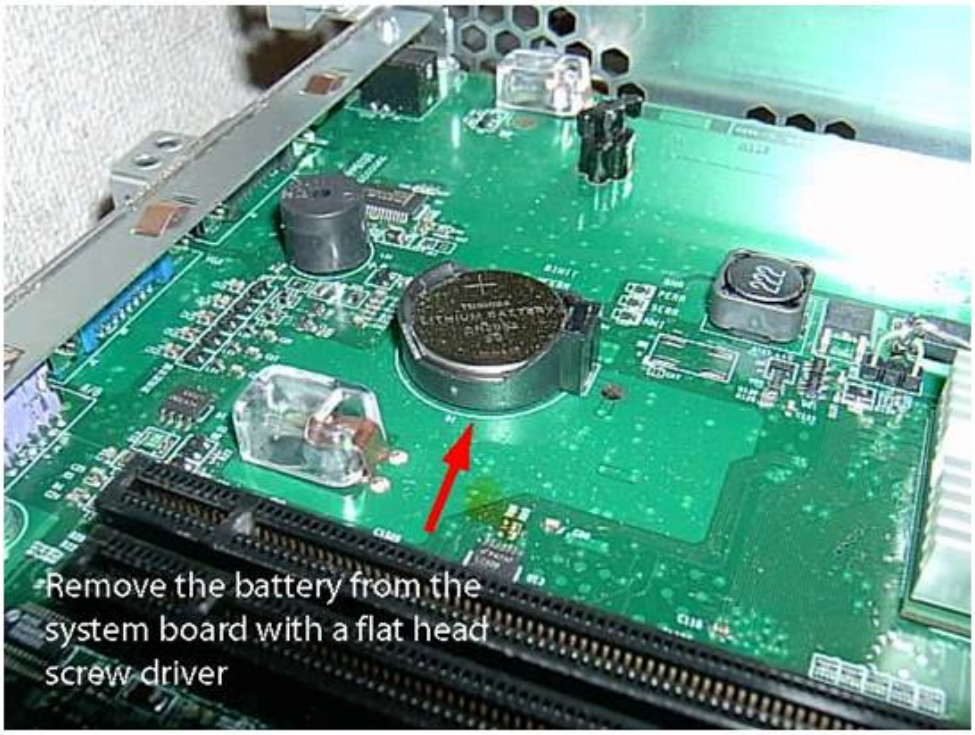


1 battery located on the SAS controller Item #7

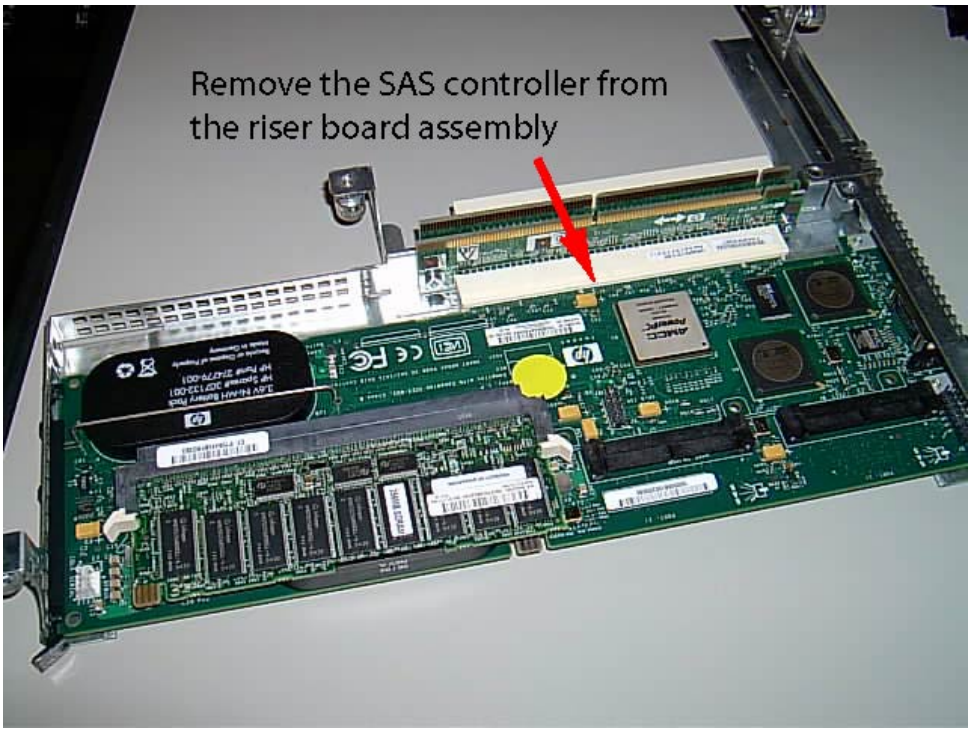
1 battery located on the system board Item #8

7 capacitors located in the power supply Item #3

Attachment 1

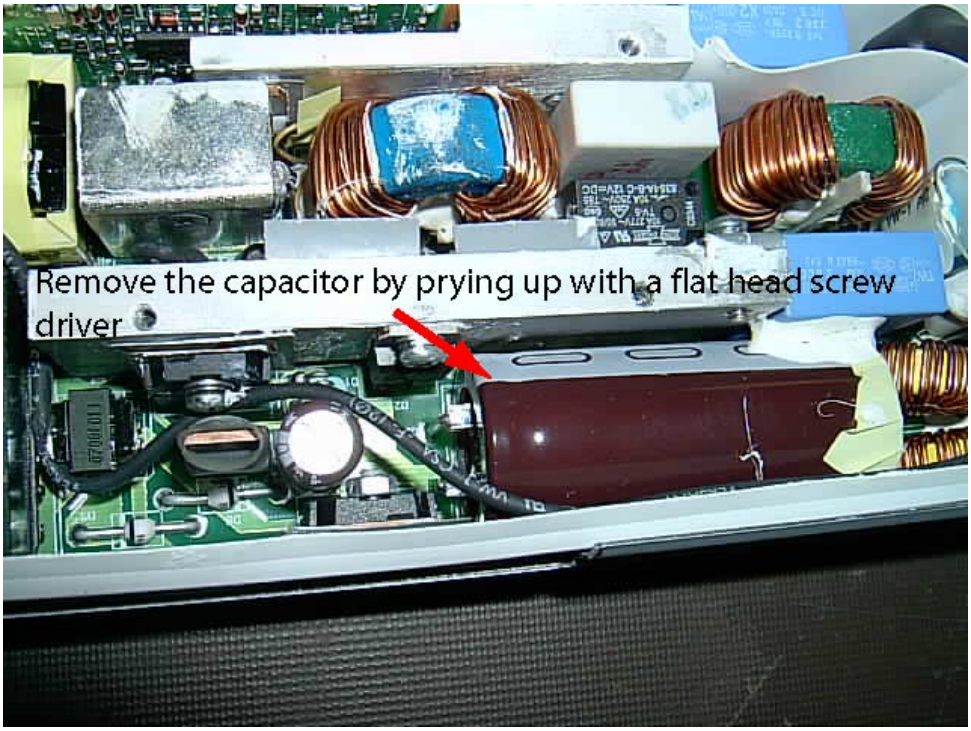


Attachment 2

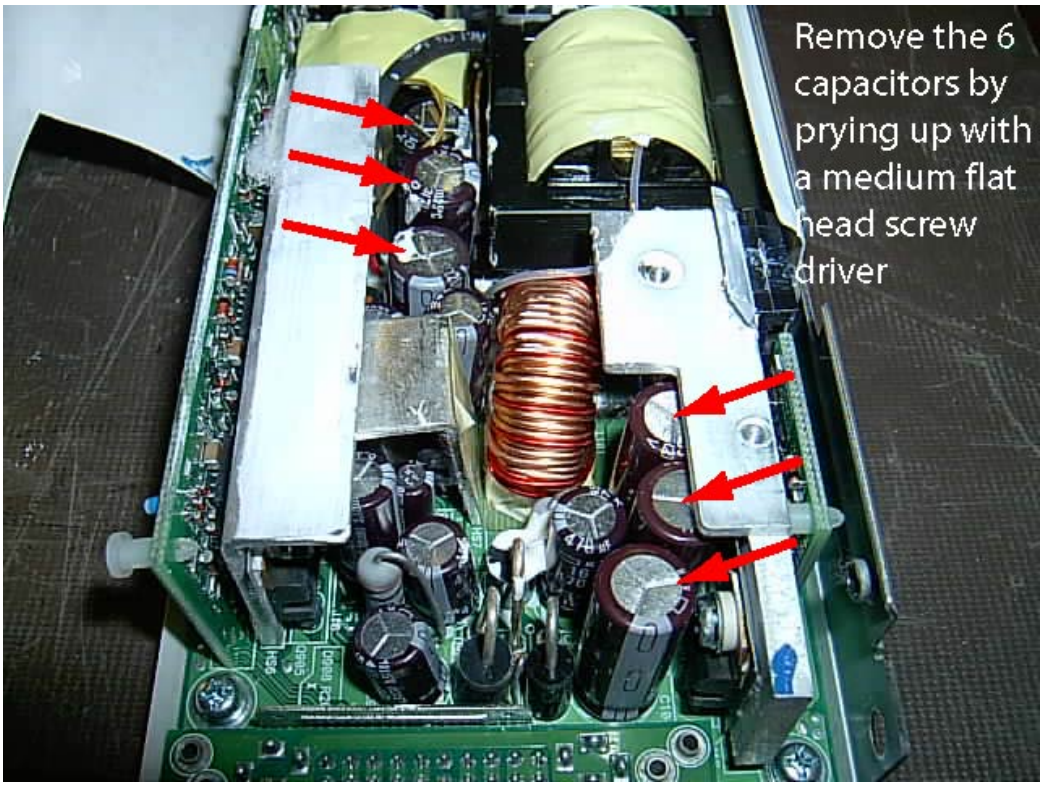


Attachment 3

Attachment 4



Attachment 5



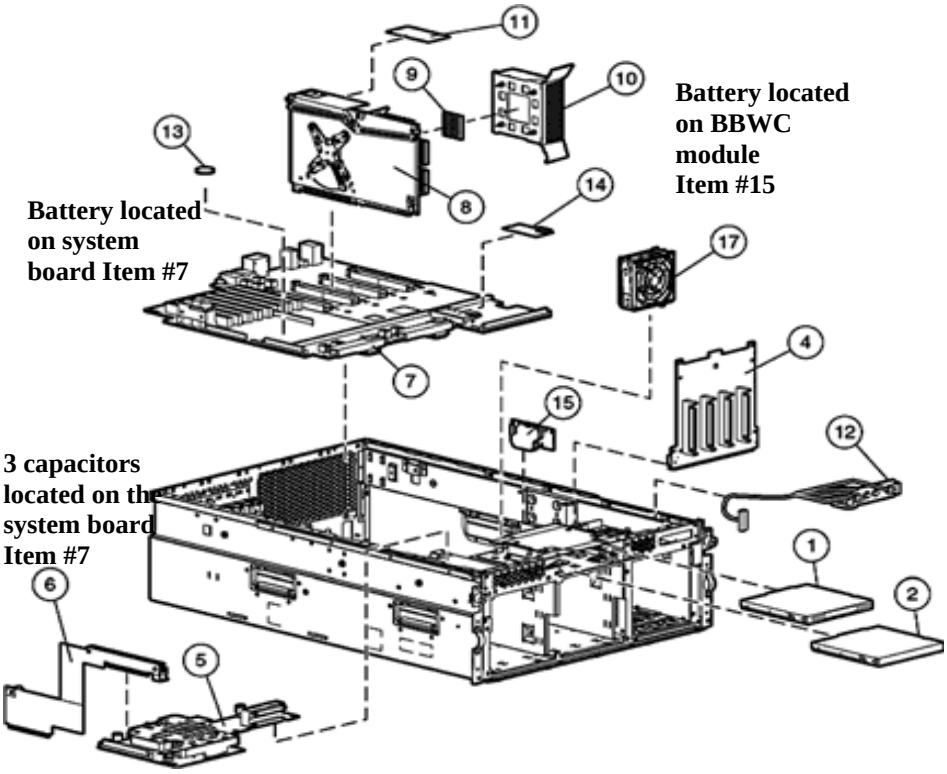
Attachment 6

End of DL360 G4p instructions

1	System Board Battery – Remove the top cover and locate the battery on the system board. With a medium flat head screw driver remove the battery and dispose of properly.
2	Battery Backed Module – With the top cover removed locate the BBWC module with the battery on the side of the chassis then remove and dispose of properly.
3	Capacitors > 2.5CM – With the top cover removed locate the capacitors on the system board and pry from the PCB with a medium flat head screw driver and dispose of properly.
4	Capacitors > 2.5CM – Remove the power supply(s) from the system. With #2 Philips screw driver remove the screws securing the top cover then locate the capacitors and pry from the PCB with a medium flat head screw driver and dispose of properly.
5	
6	
7	

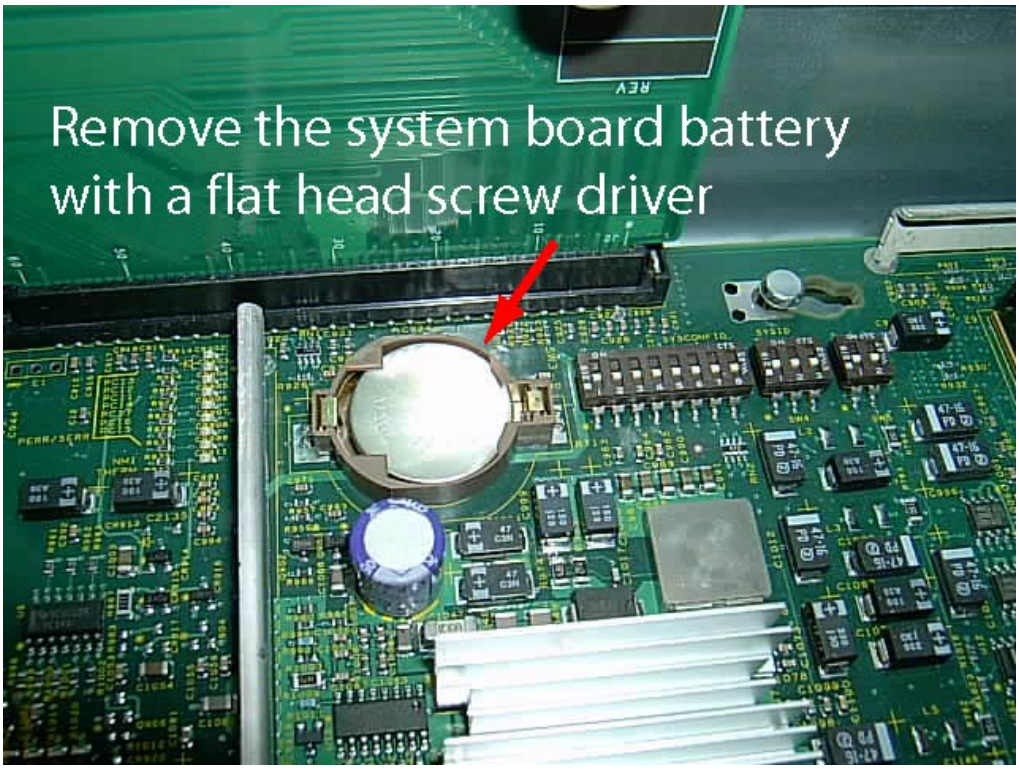
OPTIONAL: Depending upon the complexity of the disassembly process, a graphic depicting the locations of items contained within the product which require selective treatment (with descriptions and arrows identifying locations) can be inserted below:

Attachment 7 – Disassembly Diagram Attachment 8 – System Battery Location Attachment 9 – Battery Backed Module Location Attachment 10 – System Board Capacitor Location Attachment 11, 12, 13 & 14 – Power Supply Capacitor Locations

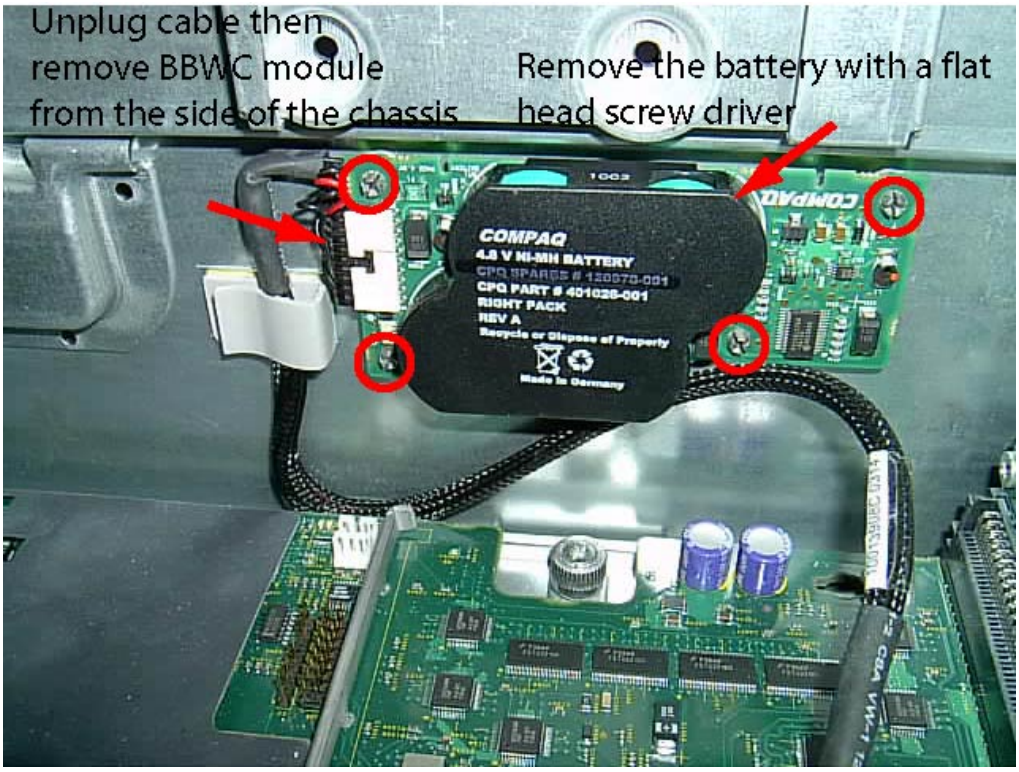


23 capacitors located in the power supply in side the front of the system (Not shown)

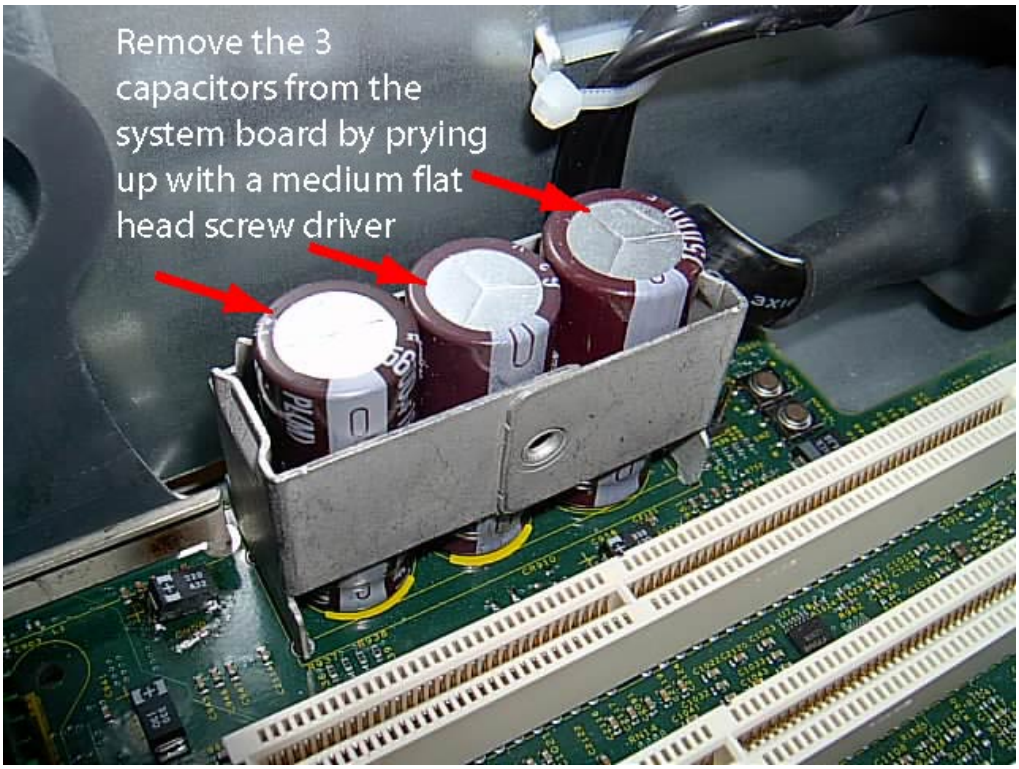
Attachment 7



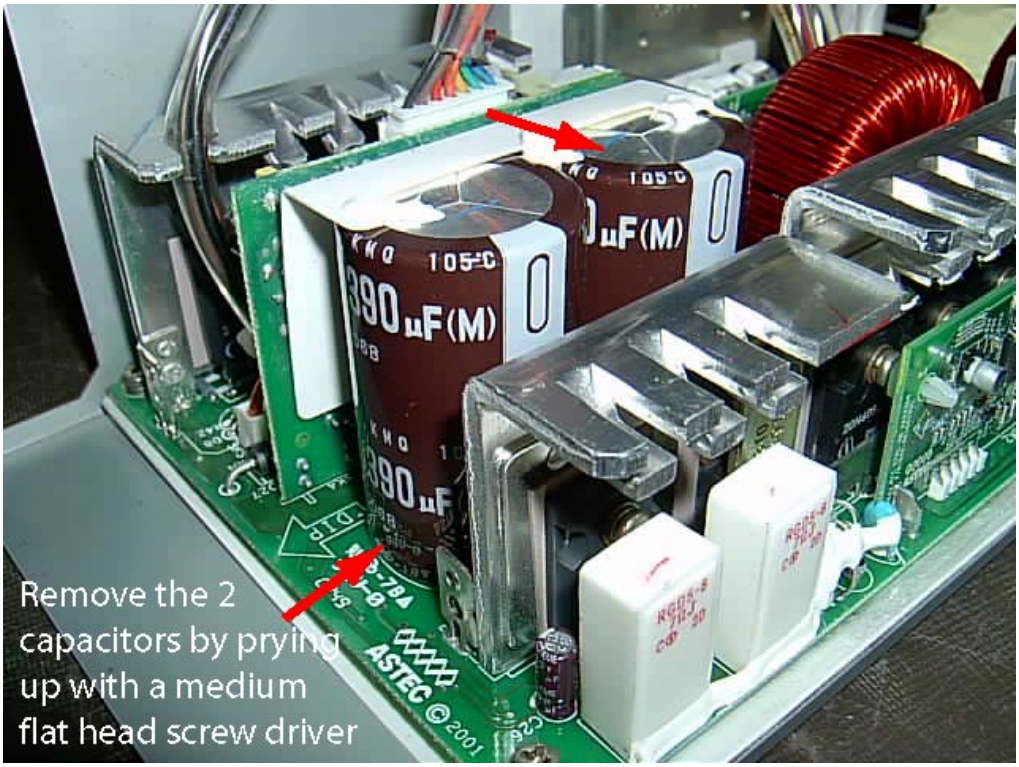
Attachment 8



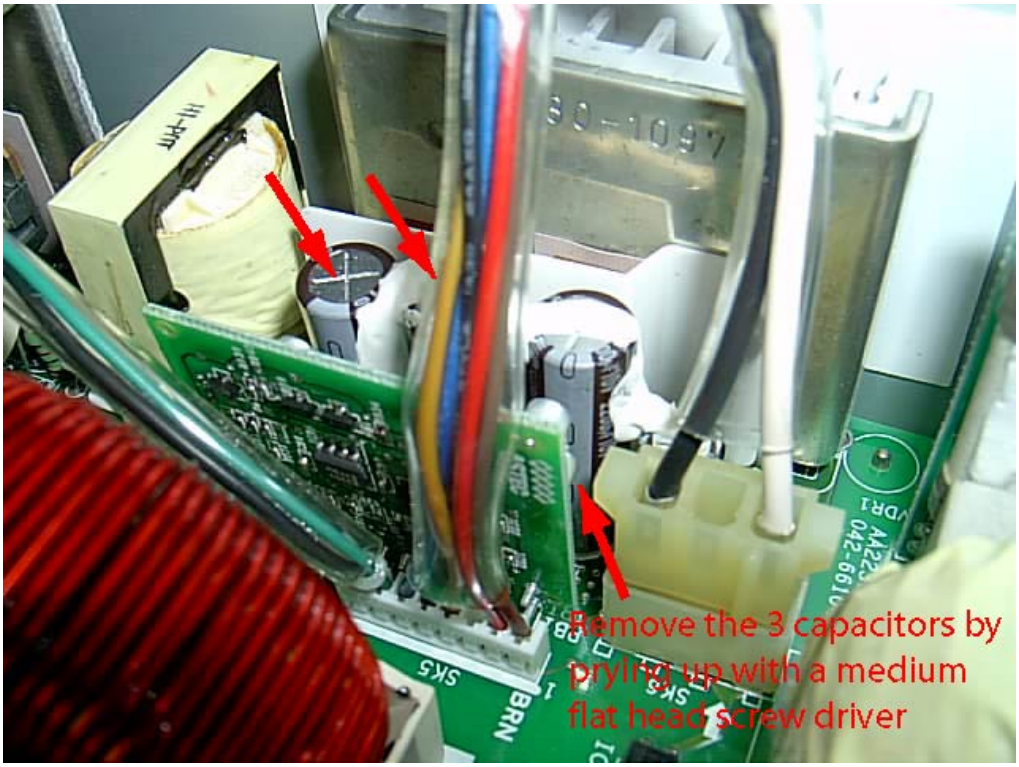
Attachment 9



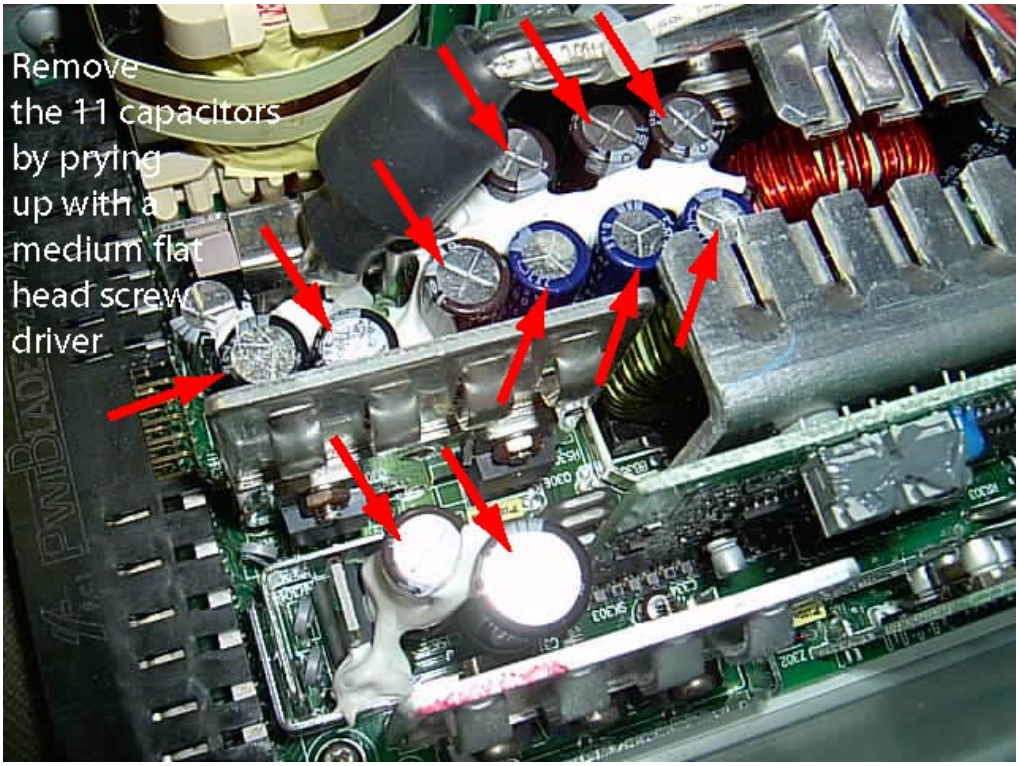
Attachment 10



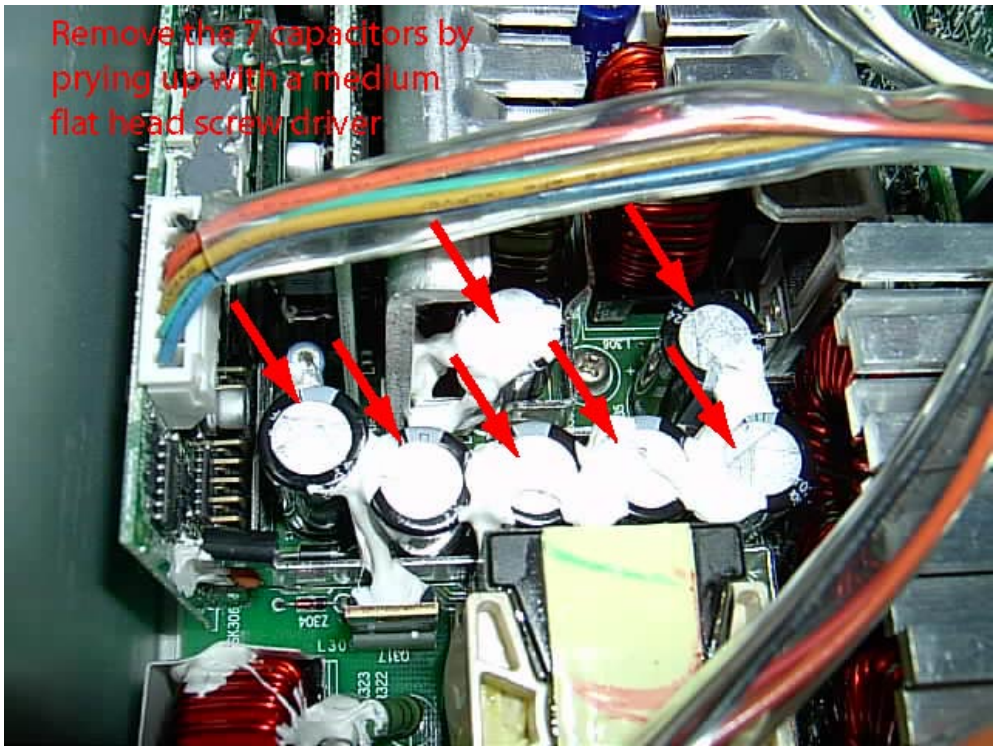
Attachment 11



Attachment 12



Attachment 13



Attachment 14